

50A, 60V, Avalanche Rated N-Channel Enhancement-Mode Power MOSFETs

December 1995

Features

- 50A, 60V
- $r_{DS(ON)} = 0.022\Omega$
- *Temperature Compensating* PSPICE Model
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- +175°C Operating Temperature

Description

The RFG50N06, RFP50N06, RF1S50N06, and RF1S50N06SM N-Channel power MOSFETs are manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI integrated circuits gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers, and relay drivers. These transistors can be operated directly from integrated circuits.

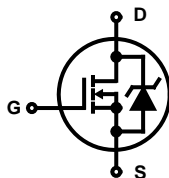
PACKAGE AVAILABILITY

| PART NUMBER | PACKAGE | BRAND |
|-------------|----------|----------|
| RFG50N06 | TO-247 | RFG50N06 |
| RFP50N06 | TO-220AB | RFP50N06 |
| RF1S50N06 | TO-262AA | F1S50N06 |
| RF1S50N06SM | TO-263AB | F1S50N06 |

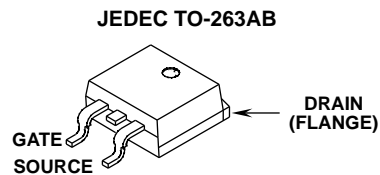
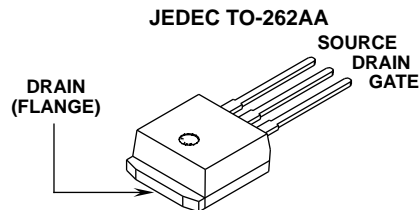
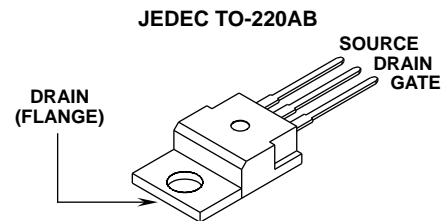
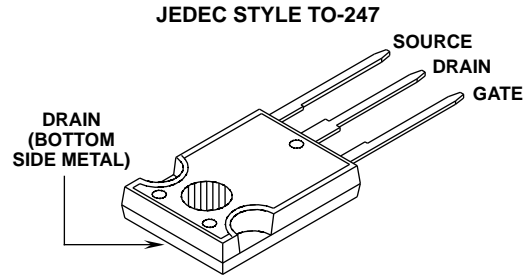
NOTE: When ordering, use the entire part number. Add the suffix, 9A, to obtain the TO-263AB variant in tape and reel, i.e. RF1S50N06SM9A.

Formerly developmental type TA49018.

Symbol



Packages



Absolute Maximum Ratings $T_C = +25^\circ\text{C}$

| | | RFG50N06, RFP50N06 RF1S50N06, RF1S50N06SM | UNITS |
|-----------------------------------|----------------|--|-------|
| Drain Source Voltage | V_{DS} | 60 | V |
| Drain Gate Voltage | V_{DGR} | 60 | V |
| Gate Source Voltage | V_{GS} | ± 20 | V |
| Drain Current | I_D | 50 | A |
| RMS Continuous | I_{DM} | Refer to Peak Current Curve | |
| Pulsed Drain Current | E_{AS} | Refer to UIS Curve | |
| Pulsed Avalanche Rating | I_{AM} | 125 | A |
| Maximum Avalanche Current | P_D | 131 | W |
| Power Dissipation | P_T | 0.877 | W/°C |
| $T_C = +25^\circ\text{C}$ | T_{STG}, T_J | -55 to +175 | °C |
| Derate above +25°C | | | |
| Operating and Storage Temperature | | | |

Specifications RFG50N06, RFP50N06, RF1S50N06, RF1S50N06SM

Electrical Specifications $T_C = +25^\circ\text{C}$, Unless Otherwise Specified.

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN | TYP | MAX | UNITS | |
|--|-----------------|--|------------------------------|---|-------|--------------------|---------------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$ | 60 | - | - | V | |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}$, $I_D = 250\mu\text{A}$ | 2 | - | 4 | V | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 60\text{V}$, $V_{GS} = 0\text{V}$ | $T_C = +25^\circ\text{C}$ | - | - | 1 | μA |
| | | | $T_C = +150^\circ\text{C}$ | - | - | 50 | μA |
| Gate-Source Leakage Current | I_{GSS} | $V_{GS} = \pm 20\text{V}$ | - | - | 100 | nA | |
| On Resistance | $r_{DS(ON)}$ | $I_D = 50\text{A}$, $V_{GS} = 10\text{V}$ | - | - | 0.022 | Ω | |
| Turn-On Time | t_{ON} | $V_{DD} = 30\text{V}$, $I_D = 50\text{A}$ $R_L = 0.6\Omega$, $V_{GS} = +10\text{V}$ $R_{GS} = 3.6\Omega$ | - | - | 95 | ns | |
| Turn-On Delay Time | $t_{D(ON)}$ | | - | 12 | - | ns | |
| Rise Time | t_R | | - | 55 | - | ns | |
| Turn-Off Delay Time | $t_{D(OFF)}$ | | - | 37 | - | ns | |
| Fall Time | t_F | | - | 13 | - | ns | |
| Turn-Off Time | t_{OFF} | | - | - | 75 | ns | |
| Total Gate Charge | $Q_{G(TOT)}$ | | $V_{GS} = 0$ to 20V | $V_{DD} = 48\text{V}$, $I_D = 50\text{A}$, $R_L = 0.96\Omega$ | - | 125 | 150 |
| Gate Charge at 10V | $Q_{G(10)}$ | $V_{GS} = 0$ to 10V | - | | 67 | 80 | nC |
| Threshold Gate Charge | $Q_{G(TH)}$ | $V_{GS} = 0$ to 2V | - | | 3.7 | 4.5 | nC |
| Input Capacitance | C_{ISS} | $V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$ | - | 2020 | - | pF | |
| Output Capacitance | C_{OSS} | | - | 600 | - | pF | |
| Reverse Transfer Capacitance | C_{RSS} | | - | 200 | - | pF | |
| Thermal Resistance Junction to Case | $R_{\theta JC}$ | | - | - | 1.14 | $^\circ\text{C/W}$ | |
| Thermal Resistance Junction to Ambient | $R_{\theta JA}$ | | - | - | 80 | $^\circ\text{C/W}$ | |

Source-Drain Diode Specifications

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|-----------------------|----------|--|-----|-----|-----|-------|
| Forward Voltage | V_{SD} | $I_{SD} = 50\text{A}$ | - | - | 1.5 | V |
| Reverse Recovery Time | t_{RR} | $I_{SD} = 50\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$ | - | - | 125 | ns |

Typical Performance Curves

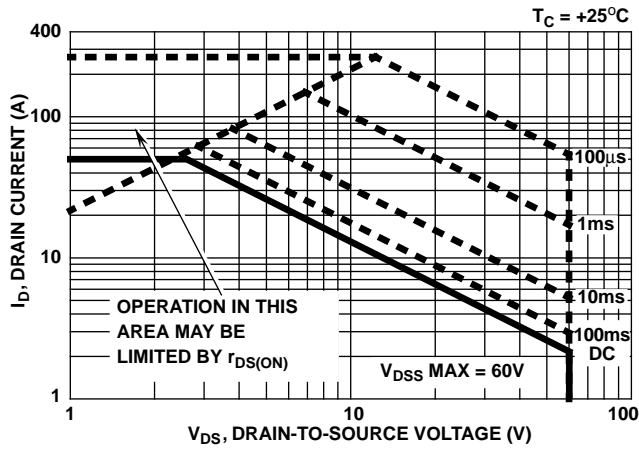


FIGURE 1. SAFE OPERATING AREA CURVE

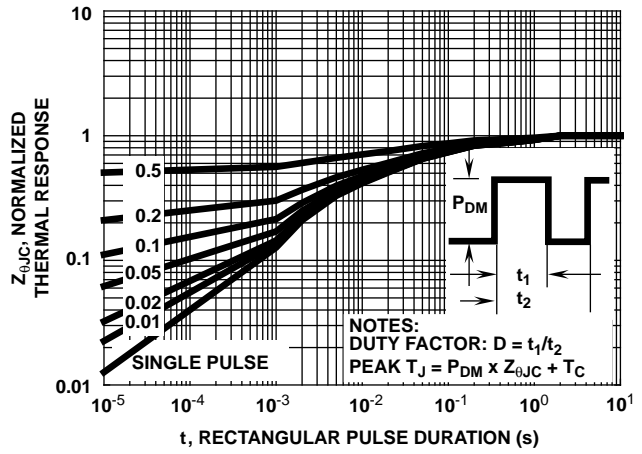


FIGURE 2. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

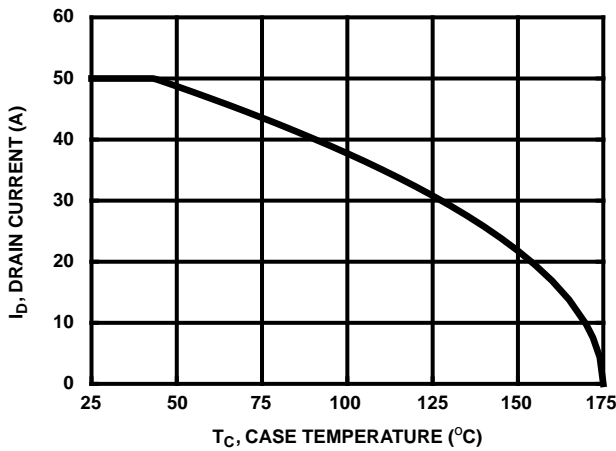


FIGURE 3. MAXIMUM CONTINUOUS DRAIN CURRENT vs TEMPERATURE

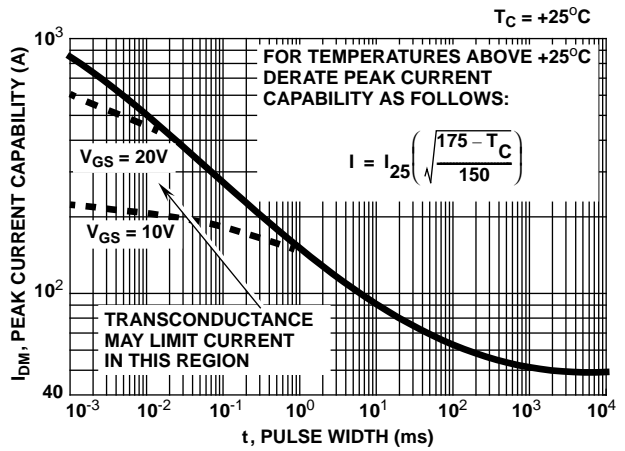


FIGURE 4. PEAK CURRENT CAPABILITY

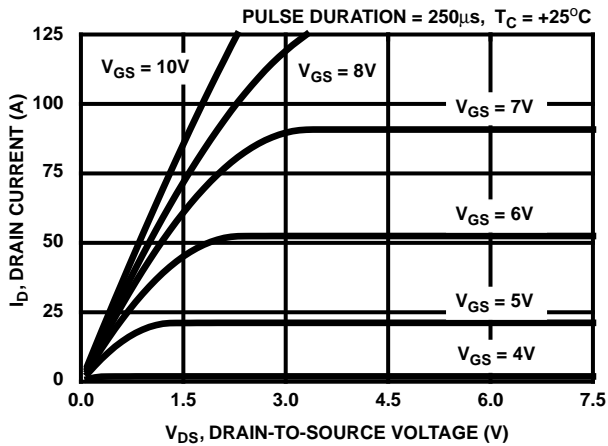


FIGURE 5. TYPICAL SATURATION CHARACTERISTICS

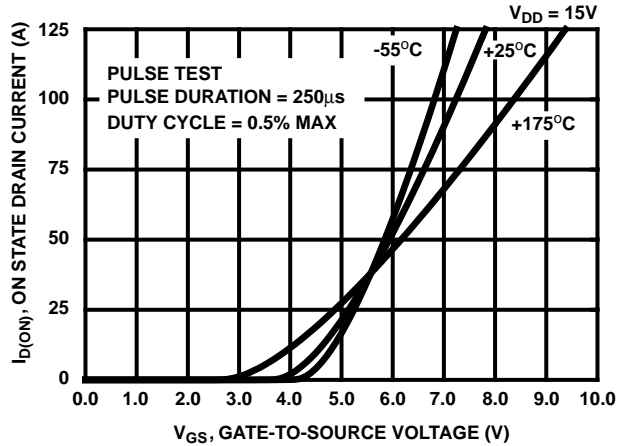


FIGURE 6. TYPICAL TRANSFER CHARACTERISTICS

Typical Performance Curves (Continued)

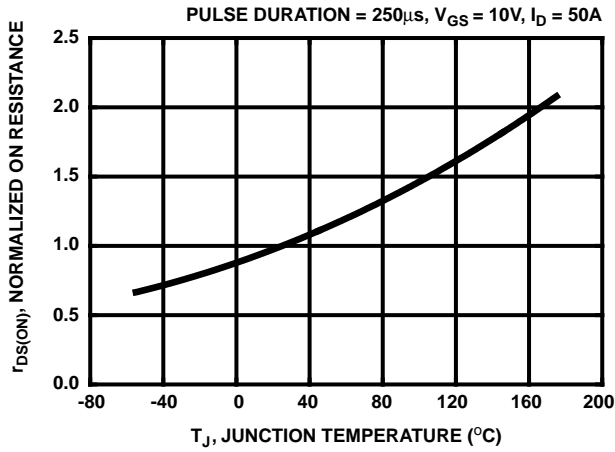


FIGURE 7. NORMALIZED $r_{DS(ON)}$ vs JUNCTION TEMPERATURE

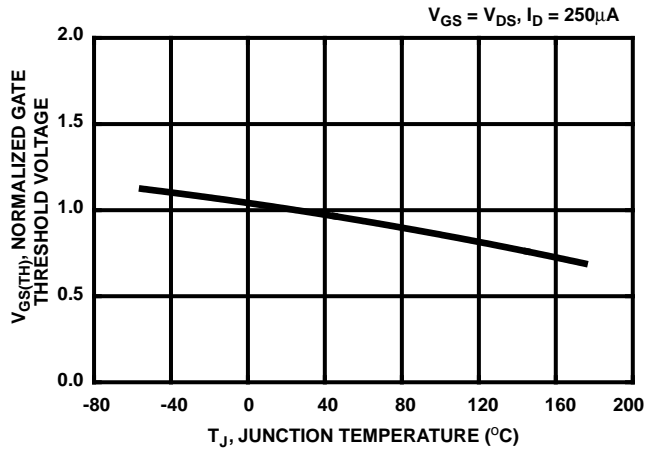


FIGURE 8. NORMALIZED GATE THRESHOLD VOLTAGE vs TEMPERATURE

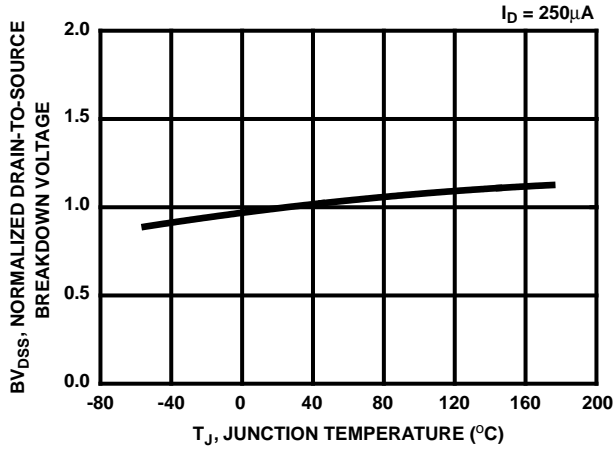


FIGURE 9. NORMALIZED DRAIN SOURCE BREAKDOWN VOLTAGE vs TEMPERATURE

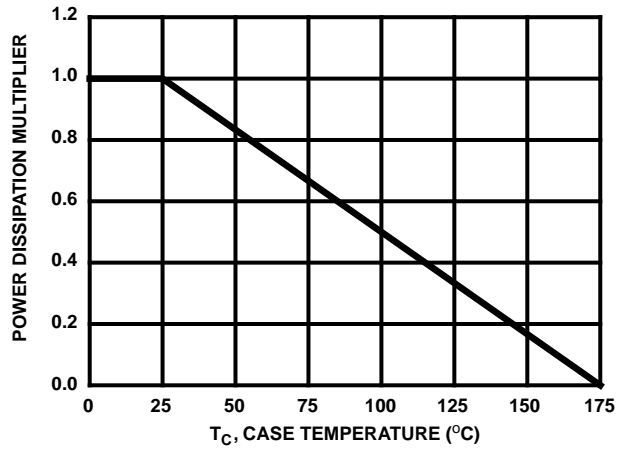


FIGURE 10. NORMALIZED POWER DISSIPATION vs TEMPERATURE DERATING CURVE

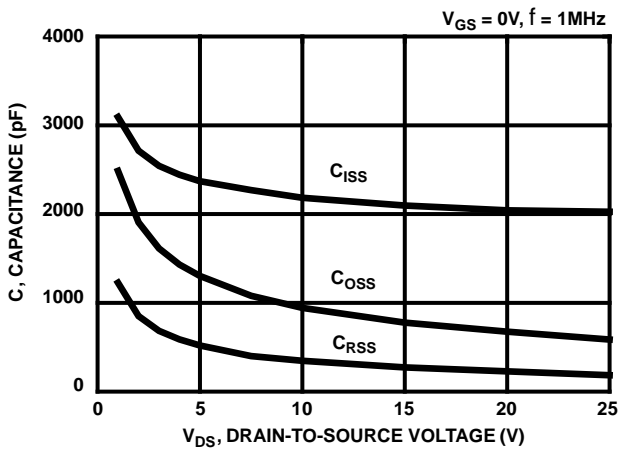


FIGURE 11. TYPICAL CAPACITANCE vs VOLTAGE

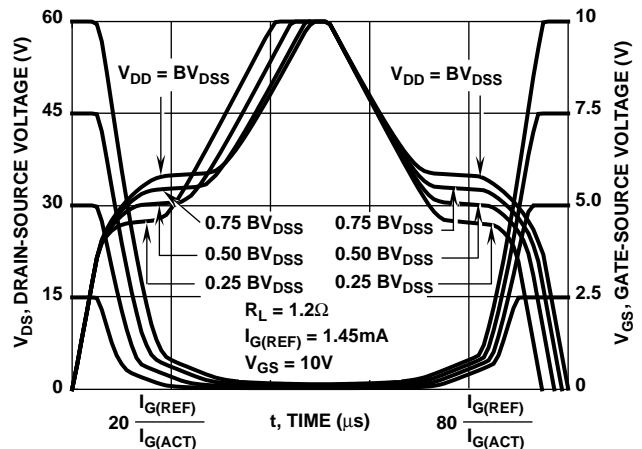


FIGURE 12. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT. REFER TO APPLICATION NOTE AN7254 AND AN7260

Typical Performance Curves (Continued)

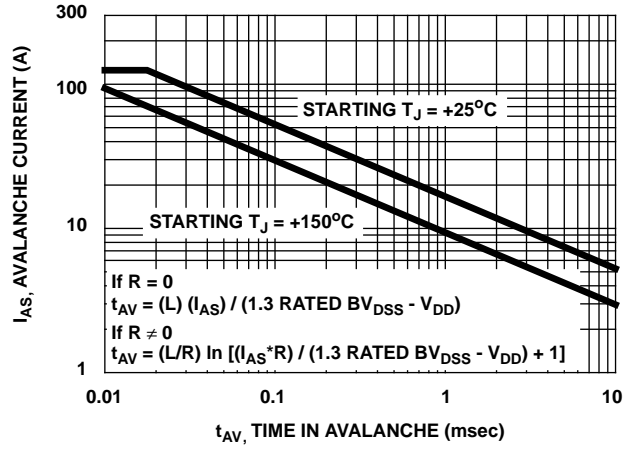


FIGURE 13. UNCLAMPED INDUCTIVE SWITCHING

Test Circuits and Waveforms

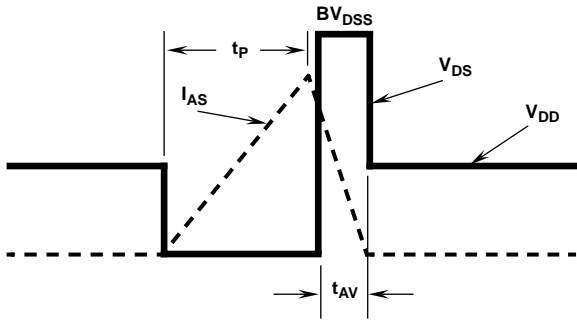


FIGURE 14. UNCLAMPED ENERGY WAVEFORMS

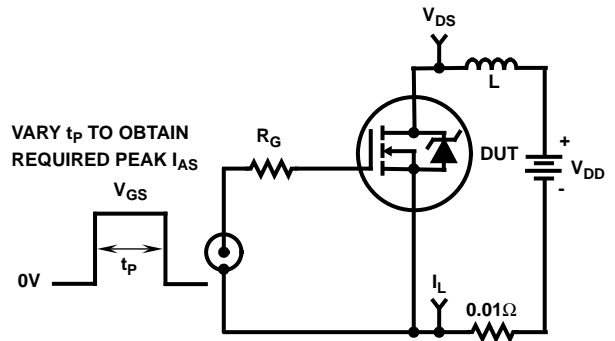


FIGURE 15. UNCLAMPED ENERGY TEST CIRCUIT

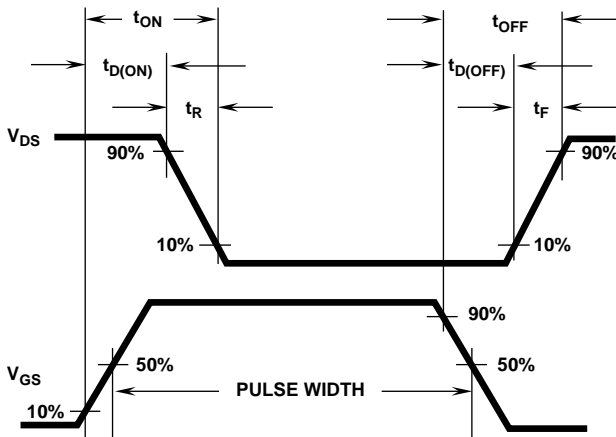


FIGURE 16. RESISTIVE SWITCHING WAVEFORMS

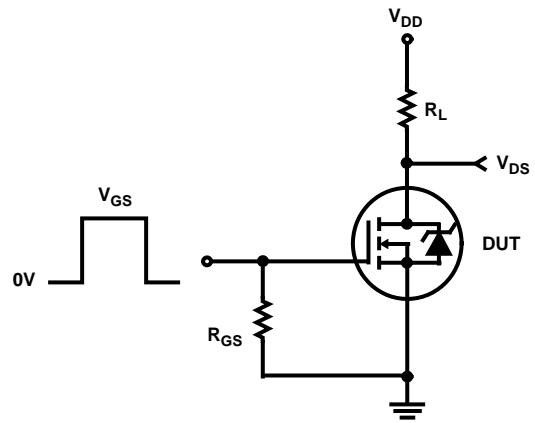


FIGURE 17. RESISTIVE SWITCHING TEST CIRCUIT

RFG50N06, RFP50N06, RF1S50N06, RF1S50N06SM

**Temperature Compensated PSPICE Model for the
RFG50N06, RFP50N06, RF1S50N06, RF1S50N06SM**

.SUBCKT RFP50N06 2 1 3
REV 2/22/93
* NOM TEMP = +25°C

CA 12 8 3.68e-9
CB 15 14 3.625e-9
CIN 6 8 1.98e-9

DBODY 7 5 DBDMOD
DBREAK 5 11 DBKMOD
DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 64.59
EDS 14 8 5 8 1
EGS 13 8 6 8 1
ESG 6 10 6 8 1
EVTO 20 6 18 8 1

IT 8 17 1

LDRAIN 2 5 1e-9
LGATE 1 9 5.65e-9
LSOURCE 3 7 4.13e-9

MOS1 16 6 8 8 MOSMOD M=0.99
MOS2 16 21 8 8 MOSMOD M=0.01

RBREAK 17 18 RBKMOD 1
RDRAIN 5 16 RDSMOD 1e-4
RGATE 9 20 0.690
RIN 6 8 1e9
RSOURCE 8 7 RDSMOD 12e-3
RVTO 18 19 RVTOMOD 1

S1A 6 12 13 8 S1AMOD
S1B 13 12 13 8 S1BMOD
S2A 6 15 14 13 S2AMOD
S2B 13 15 14 13 S2BMOD

VBAT 8 19 DC 1
VTO 21 6 0.678

.MODEL DBDMOD D (IS=9.851e-13 RS=4.91e-3 TRS1=2.07e-3 TRS2=2.51e-7 CJO=2.05e-9 TT=4.33e-8)
.MODEL DBKMOD D (RS=1.98e-1 TRS1=-2.35e-3 TRS2=-3.83e-6)
.MODEL DPLCAPMOD D (CJO=1.42e-9 IS=1e-30 N=10)
.MODEL MOSMOD NMOS (VTO=3.65 KP=35 IS=1e-30 N=10 TOX=1 L=1u W=1u)
.MODEL RBKMOD RES (TC1=1.23e-3 TC2=-2.34e-6)
.MODEL RDSMOD RES (TC1=5.01e-3 TC2=1.49e-5)
.MODEL RVTOMOD RES (TC1=-5.03e-3 TC2=-5.16e-6)
.MODEL S1AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-6.75 VOFF=-2.5)
.MODEL S1BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2.5 VOFF=-6.75)
.MODEL S2AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2.7 VOFF=2.3)
.MODEL S2BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=2.3 VOFF=-2.7)

.ENDS

NOTE: For further discussion of the PSPICE model consult **A New PSPICE Sub-circuit for the Power MOSFET Featuring Global Temperature Options**; authors, William J. Hepp and C. Frank Wheatley.

